

## 100V N-Channel Enhancement Mode Power MOSFET

### Description

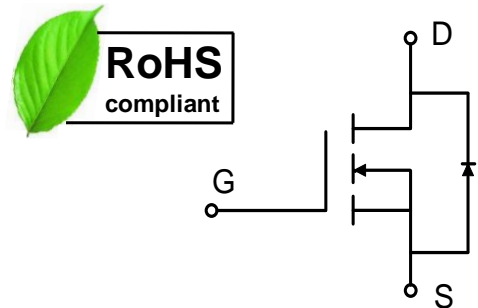
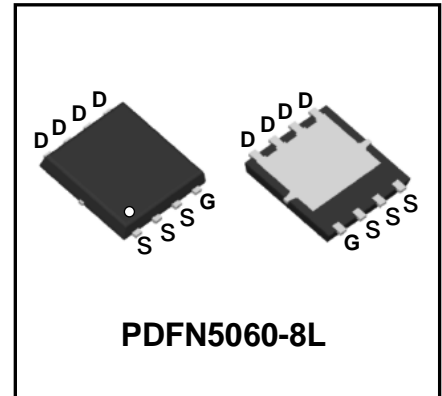
WMB128N10T2 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = 100\text{ V}$ ,  $I_D = 128\text{ A}$ (Silicon Limited)  
 $R_{DS(on)} < 4.2\text{ m}\Omega @ V_{GS} = 10\text{ V}$
- Green Device Available
- 100% EAS Guaranteed
- Optimized for High Speed Smooth Switching

### Applications

- Hard Switching and High Speed Circuit
- DC/DC Conversion
- Power Tools
- UPS
- SSR



### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup> (Silicon Limited)	$I_D$	$T_C=25^\circ\text{C}$	128
		$T_C=100^\circ\text{C}$	81
Continuous Drain Current <sup>1</sup> (Package Limited)		$T_C=25^\circ\text{C}$	60
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	400	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	180	mJ
Avalanche Current	$I_{AS}$	60	A
Total Power Dissipation <sup>4</sup>	$P_D$	$T_C=25^\circ\text{C}$	126
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	49.5	$^\circ\text{C/W}$
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	1	$^\circ\text{C/W}$

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V	
Gate-body Leakage Current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$I_{DSS}$	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1	$\mu A$
	$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V	
Drain-Source On-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	3.6	4.2	m $\Omega$	
Forward Transconductance	$g_{fs}$	$V_{DS} = 5V, I_D = 20A$	-	49.3	-	S	
<b>Dynamic Characteristics</b>							
Input Capacitance	$C_{iss}$	$V_{DS} = 50V, V_{GS} = 0V, f = 1\text{MHz}$	-	3680	-	$\mu F$	
Output Capacitance	$C_{oss}$		-	865	-		
Reverse Transfer Capacitance	$C_{rss}$		-	48	-		
<b>Switching Characteristics</b>							
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$	-	1.1	-	$\Omega$	
Total Gate Charge	$Q_g$	$V_{GS} = 10V, V_{DD} = 50V, I_D = 20A$	-	73	-	nC	
Gate-Source Charge	$Q_{gs}$		-	9.1	-		
Gate-Drain Charge	$Q_{gd}$		-	33	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 50V, R_G = 10\Omega, I_D = 20A$	-	12.5	-	nS	
Rise Time	$t_r$		-	18	-		
Turn-Off Delay Time	$t_{d(off)}$		-	43.6	-		
Fall Time	$t_f$		-	26	-		
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 20A, V_{GS} = 0V$	-	-	1.2	V	
Reverse Recovery Time	$t_{rr}$	$V_R = 50V, I_F = 20A, dI_F/dt = 500A/\mu s$	-	49	-	ns	
Reverse Recovery Charge	$Q_{rr}$		-	272	-	nC	

## Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=60A$
4. The power dissipation is limited by 150°C junction temperature

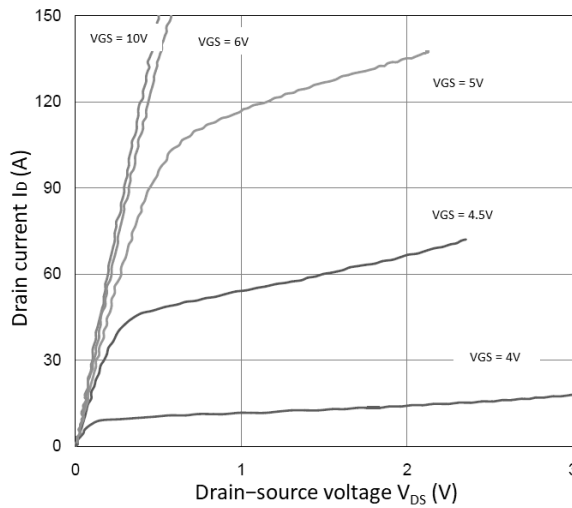


Figure 1. Output Characteristics

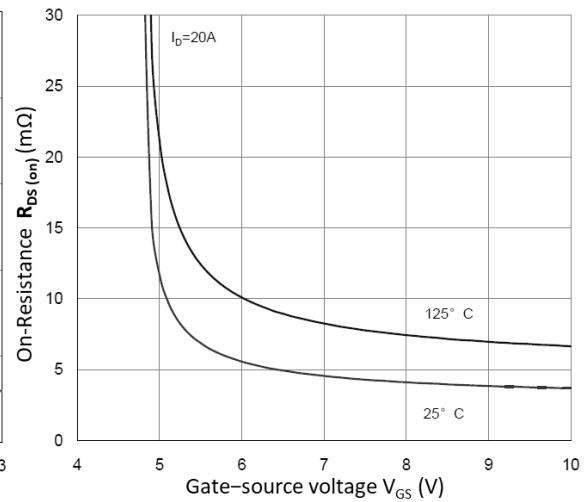


Figure 2.  $R_{DS(on)}$  vs.  $V_{GS}$

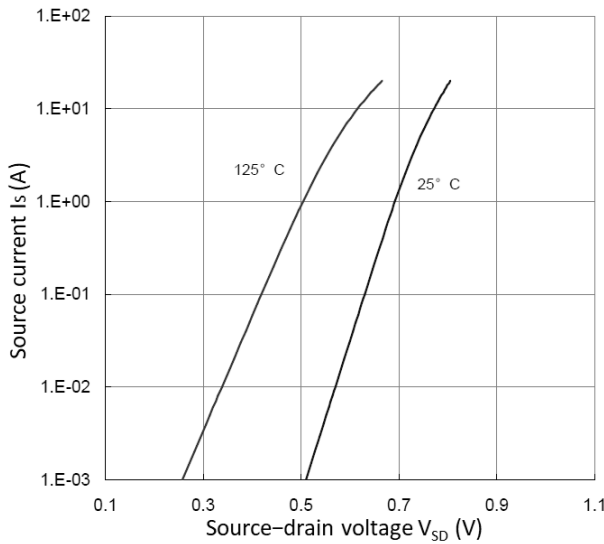


Figure3. Forward Characteristics of Reverse

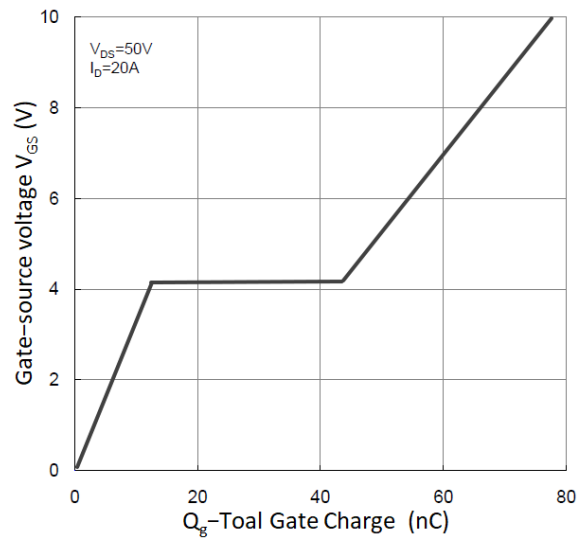


Figure4. Gate Charge Characteristics

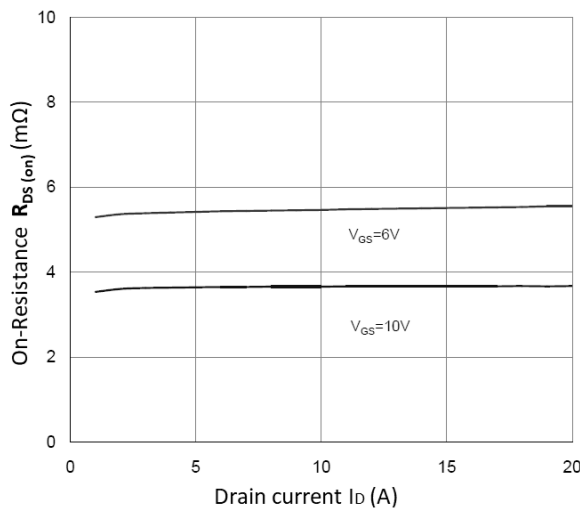


Figure 5.  $R_{DS(ON)}$  Vs  $I_D$

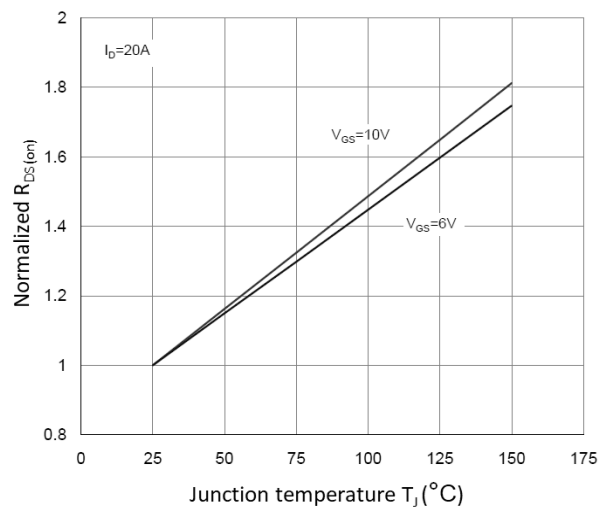


Figure 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

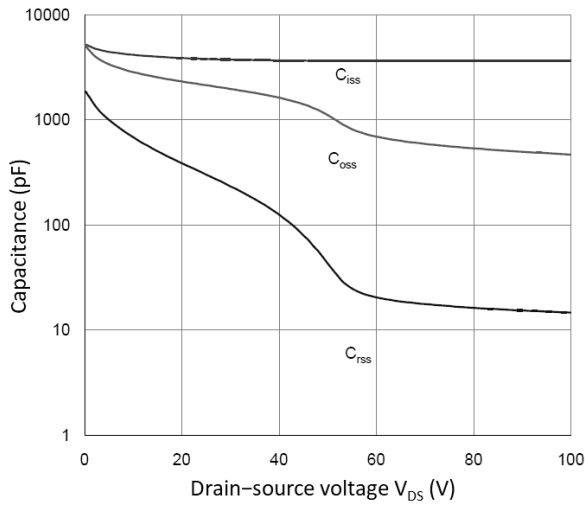


Figure 7. Capacitance Characteristics

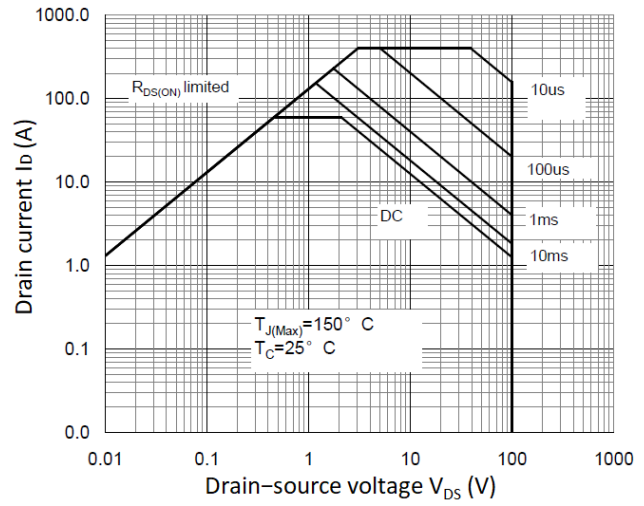


Figure 8. Safe Operating Area

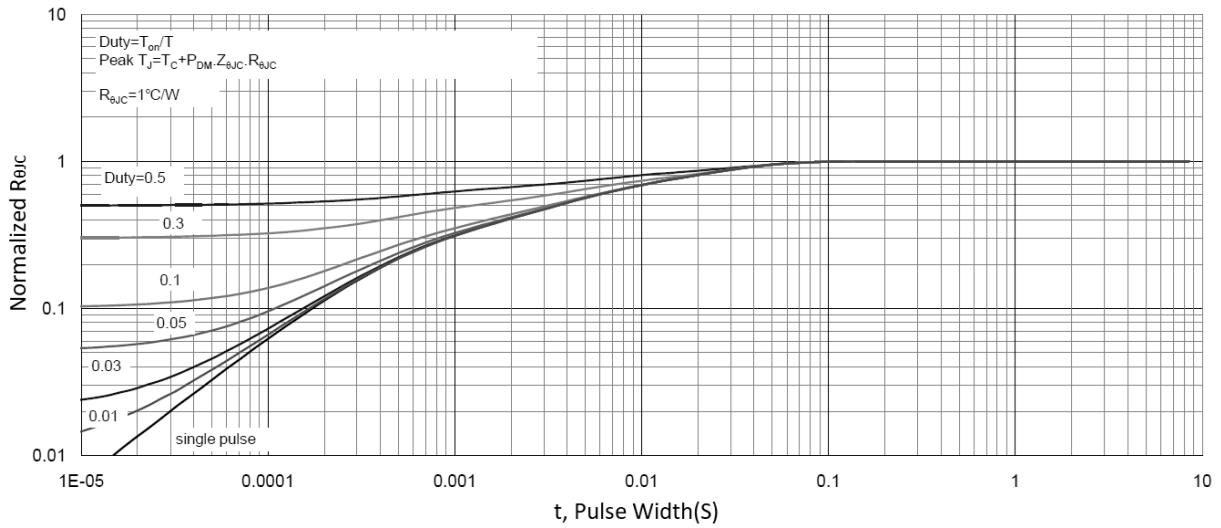


Figure 9. Normalized Maximum Transient Thermal Impedance

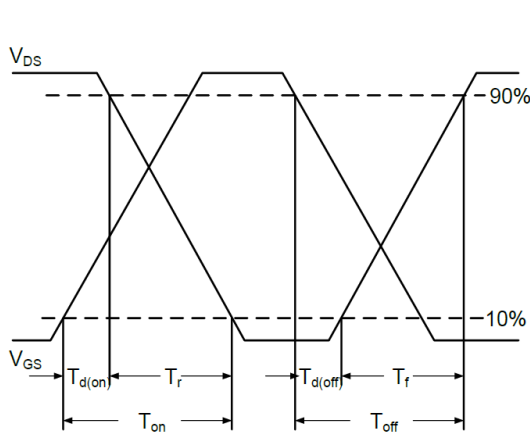


Figure 10. Switching Time Waveform

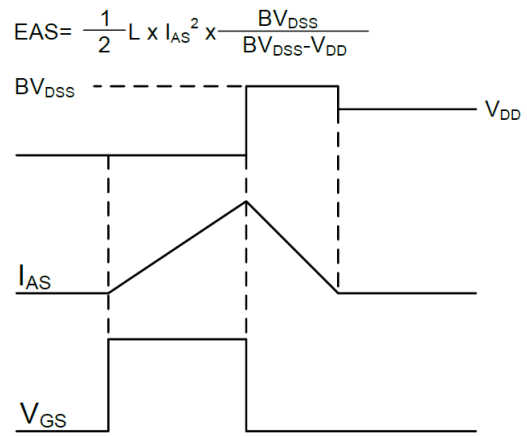
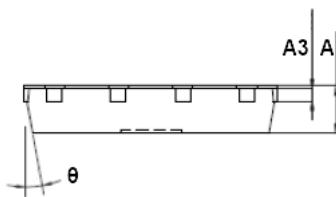
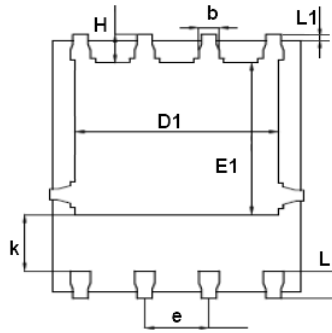
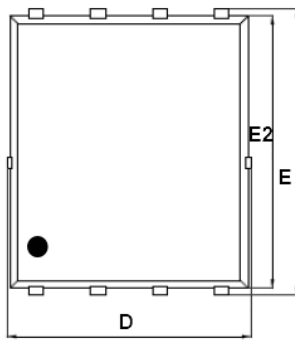


Figure 11. Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

## Mechanical Dimensions for PDFN5060-8L



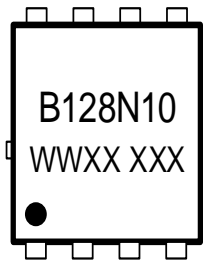
## COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.30	3.92
E2	5.65	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.61
$\theta$	0°	12°

## Ordering Information

Part	Package	Marking	Packing method
WMB128N10T2	PDFN5060-8L	B128N10	Tape and Reel

## Marking Information



B128N10= Device code

WWXX XXX= Date code

## Contact Information

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